Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L5	16	("6809421").URPN.	USPAT	OR	OFF	2006/12/09 11:30
L6	11	("4499655" "4774632" "4807021" "5229647" "5270261" "5399898" "5408123" "5618752" "5793105" "5846879" "5973396").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/09 11:32
L7	9	("3239719" "3813773" "4761681" "4807021" "4897708" "4954875" "4984358" "5089880").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/09 11:36
L8	167	("5229647").URPN.	USPAT	OR	OFF	2006/12/09 12:11
L9	1	("20010008309").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/09 12:11
L10	4	("20040017012" "4978639" "5686067" "6620731").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/09 12:18
L11	2753	(@ad<"20021219") and 438/455, 629,637,672,675,668,613,614,667, 928,977.ccls. and ((hole or aperture or plug or via or (through adj hole)) with (substrate or board or interposer or pwb or pcb))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/09 12:20
L12	83284	"119" and (dielectric or insulati\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/09 12:21
L13	2436	L11 and (dielectric or insulati\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/09 12:21
L14	2030	L13 and (fill\$3 or plug)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/09 12:22
L15	1429	L14 AND (("SI" OR silicon or semicondcutor) with (substrate or interposer or board or pwb or pcb))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/09 12:22

12/9/2006 12:32:17 PM

L16	1979	(@ad<"20021219") and 257/686, 777,774.ccls. and ((hole or aperture or plug or via or groove or (through adj hole)) with (substrate or board or interposer or pwb or pcb))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/09 12:29
L17	1351	L16 and (fill\$3 or plug)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/09 12:31
L18	1146	L17 and (dielectric or insulati\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/09 12:22
L19	621	L18 AND (("SI" OR silicon or semicondcutor) with (substrate or interposer or board or pwb or pcb))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/09 12:29
L20	1942	L14 not L19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/09 12:23
L21	1341	L15 not L19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/09 12:27
L22	1236	(@ad<"20021219") and 257/758-760.ccls. and ((hole or aperture or plug or via or groove or (through adj hole)) with (substrate or board or interposer or pwb or pcb))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/09 12:29
L23	863	L22 AND (("SI" OR silicon or semicondcutor) with (substrate or interposer or board or pwb or pcb))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/09 12:30

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L24	831	L23 not L21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/09 12:30
L25	665	L24 not L19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/09 12:30
L26	660	L24 and (fill\$3 or plug)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/09 12:32
L27	494	L25 and (fill\$3 or plug)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFE	2006/12/09 12:32
S1	1	("6831000").PN.	USPAT; USOCR	OR	OFF .	2006/12/08 16:00
S2	4	("20040017012" "4978639" "5686067" "6620731").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/08 16:45
S3	439507	(@ad<"20021219") and ("257"/\$. ccls. or "438"/\$.ccls. or "361"/\$. ccls. or "174"/\$.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/08 16:51
S4	969	S3 and (chip adj board)	US-PGPUB; USPAT; USOCR;	OR	OFF	2006/12/08 16:48
			EPO; JPO; DERWENT; IBM_TDB			
S5	969	S3 and "chip board"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/08 16:48

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S6	968	S5 not "chip and board"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/08 16:48
S7	31	S3 and (chip\$1board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT;	OR	OFF	2006/12/08 16:49
S8	1943	(@ad<"20021219") and 257/686, 777,774.ccls. and ((hole or aperture or plug or via or (through adj hole)) with (substrate or board or interposer or pwb or pcb))	IBM_TDB US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/09 12:18
S9	1979	(@ad<"20021219") and 257/686, 777,774.ccls. and ((hole or aperture or plug or via or groove or (through adj hole)) with (substrate or board or interposer or pwb or pcb))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/08 16:55
S10	1351	S9 and (fill\$3 or plug)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/09 12:22
S11	1557	S9 and (dielectric or insulati\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/09 12:21
S12	1146	S10 and (dielectric or insulati\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/08 17:10
S13	621	S12 AND (("SI" OR silicon or semicondcutor) with (substrate or interposer or board or pwb or pcb))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/09 12:22

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